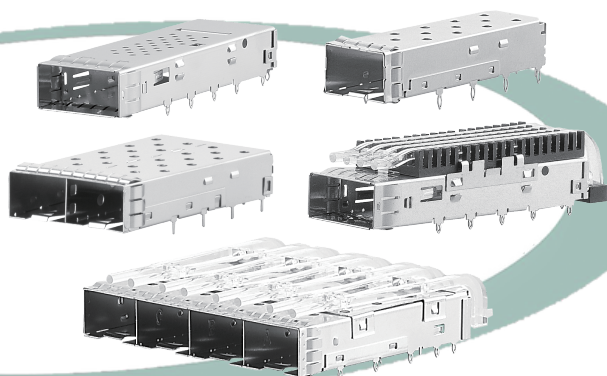


INTERCONNECT SOLUTION FOR OCP 3.0 NIC

Enablement for rapid technology development
Simplifying design decisions



SFP+ / QSFP+ Series



PRODUCT FEATURES

- Allow cloud providers and server OEMs to use compact server designs
- Common form factor interfaces "Easy" design choices
- New form factor simplifies operations to lower the total cost
- Interface commonality across form factors
- Reliable springs and gasket designs for EMI containment
- Belly to belly compatible

GENERAL SPECIFICATIONS

GENERAL SPECIFICATIONS					
PART NUMBER	CATEGORY	PORT	TERMINAL	HEAT SINK	LIGHT PIPE
KSFP-A-PPFA-0125-XXX	SFP+	1X1	PRESS FIT	WITH	WITHOUT
KSFP-A-PPFB-0105-XXX	SFP+	1X1	PRESS FIT	WITHOUT	WITHOUT
KSFP-A-PSLB-0202-XXX	SFP+	1X2	SOLDER LEAD	WITHOUT	WITHOUT
KSFP-A-PPFA-0412-XXX	SFP+	1X4	PRESS FIT	WITHOUT	WITH
KQFP-A-ZPFT-0101-XXX	QSFP 28	1X1	PRESS FIT	WITHOUT	WITHOUT
KQFP-A-ZPFT-01P1-XXX	QSFP 28	1X1	PRESS FIT	WITH	WITH

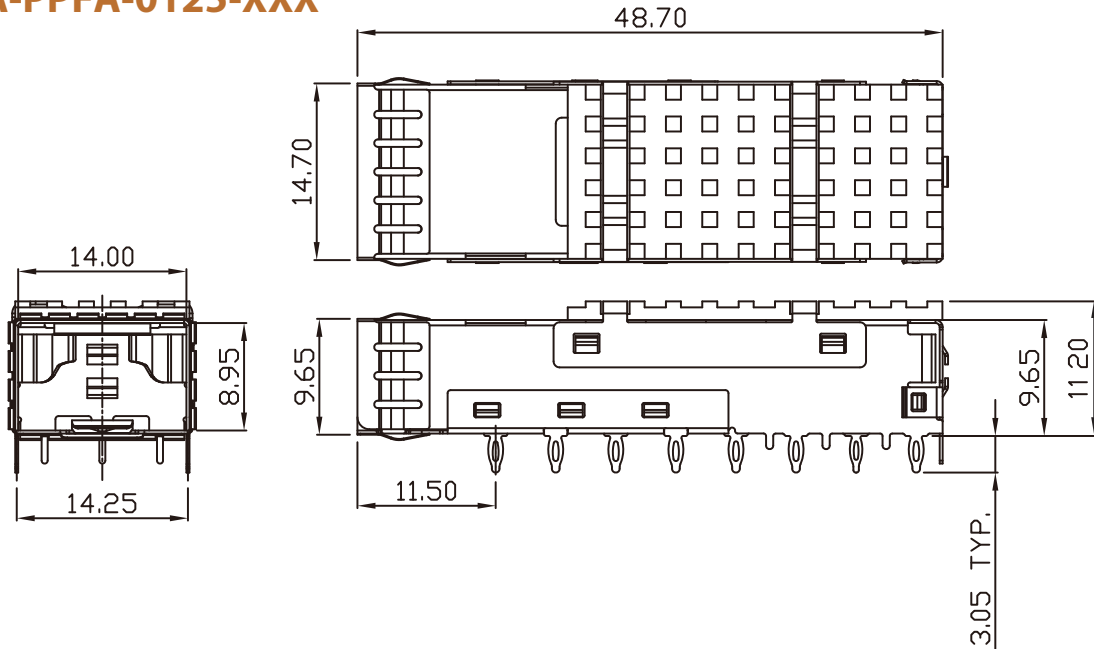


INTERCONNECT SOLUTION FOR OCP 3.0 NIC

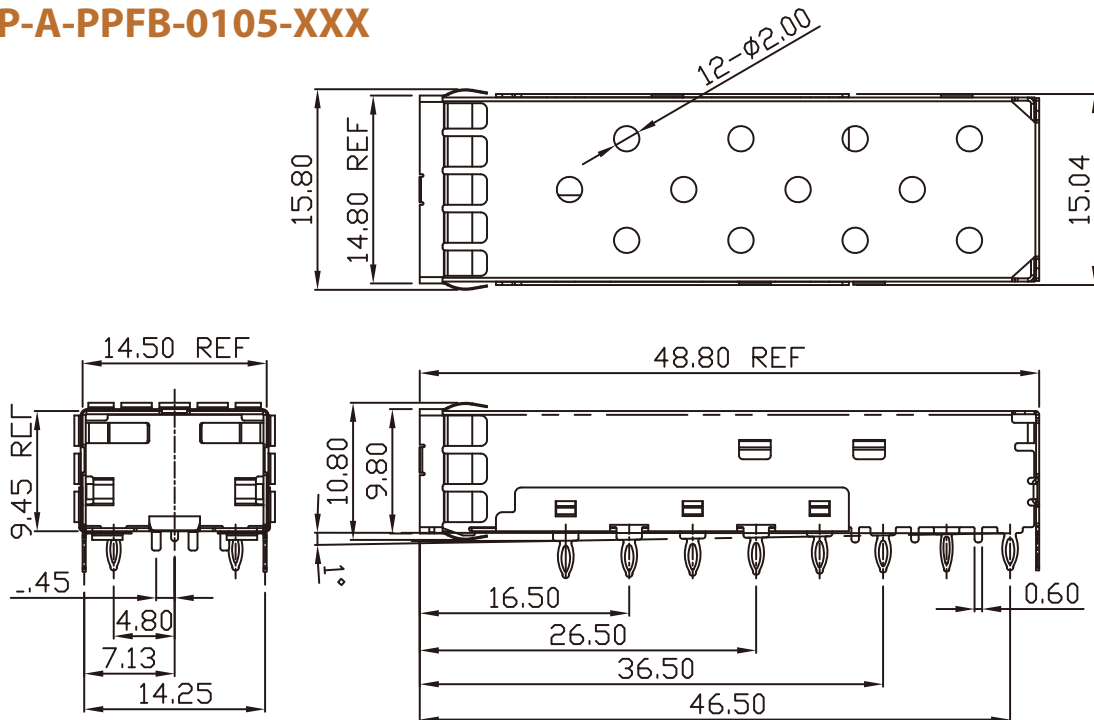
Enablement for rapid technology development
Simplifying design decisions

MECHANICAL

KSFP-A-PPFA-0125-XXX



KSFP-A-PPFB-0105-XXX

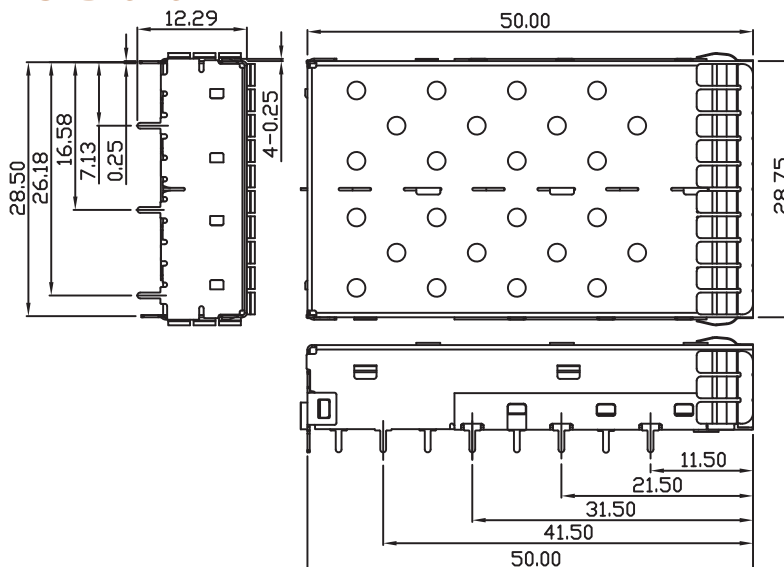


INTERCONNECT SOLUTION FOR OCP 3.0 NIC

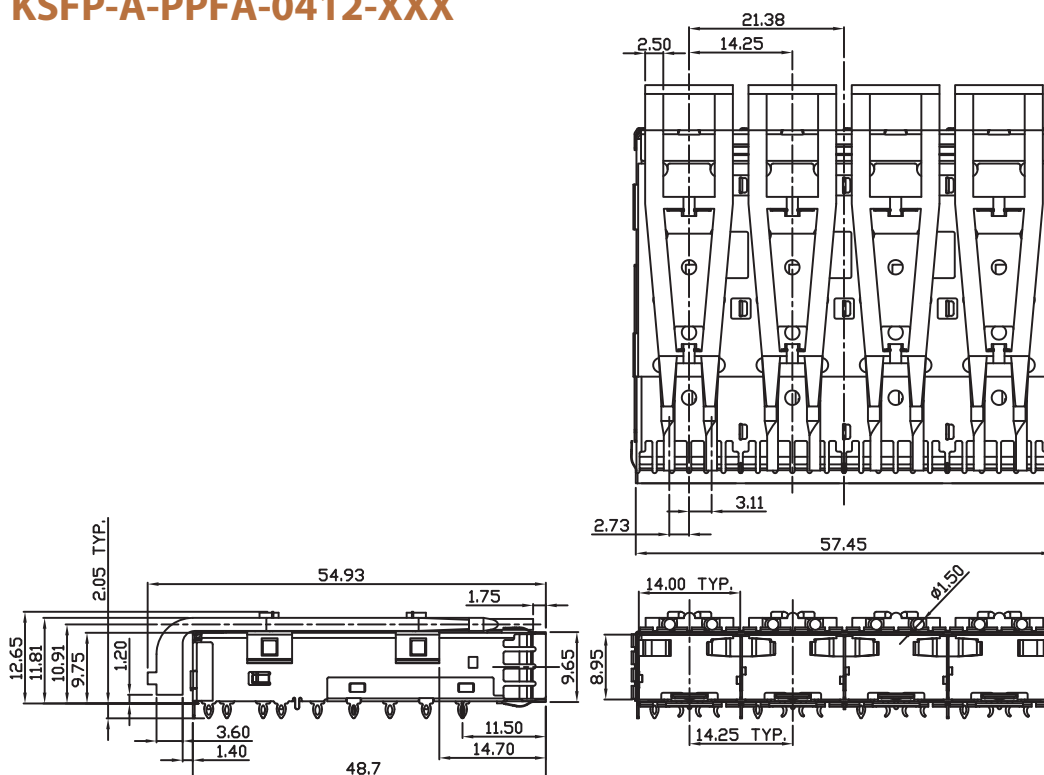
Enablement for rapid technology development
Simplifying design decisions

MECHANICAL

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KSFP-A-PPFA-0412-XXX

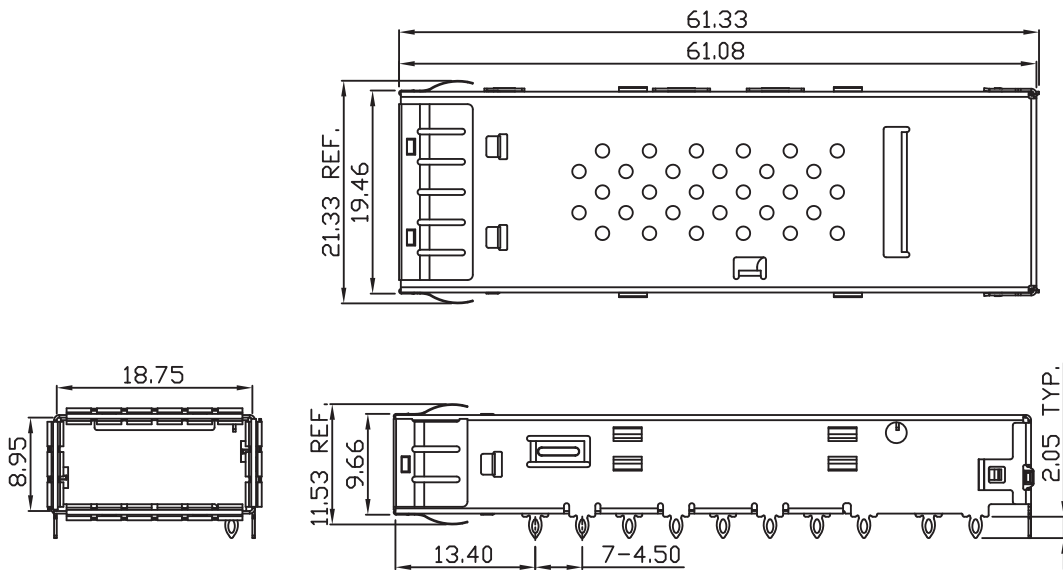


INTERCONNECT SOLUTION FOR OCP 3.0 NIC

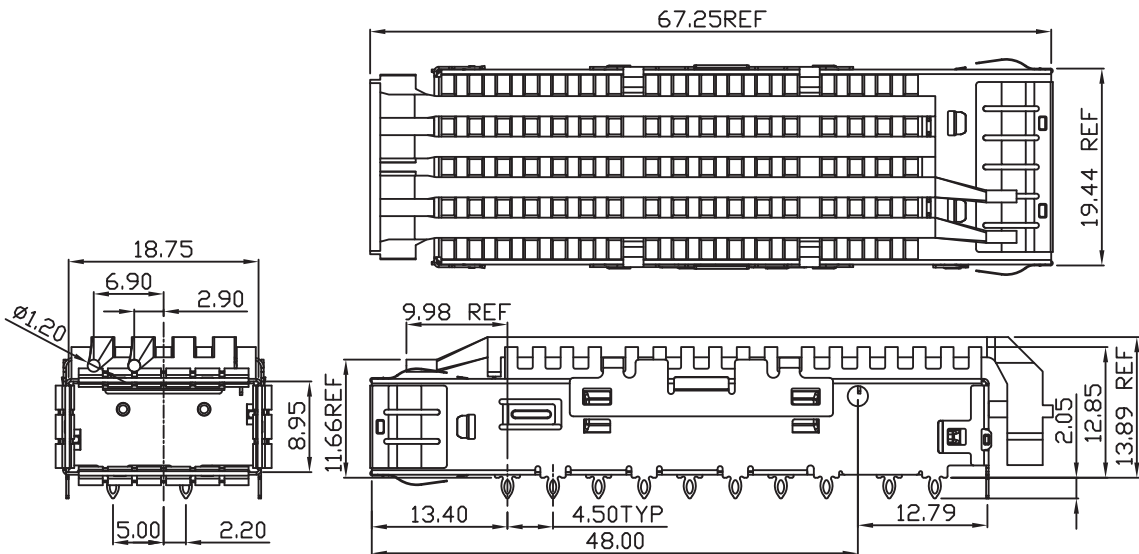
Enablement for rapid technology development
Simplifying design decisions

MECHANICAL

KQFP-A-ZPFT-0101-XXX



KQFP-A-ZPFT-01P1-XXX

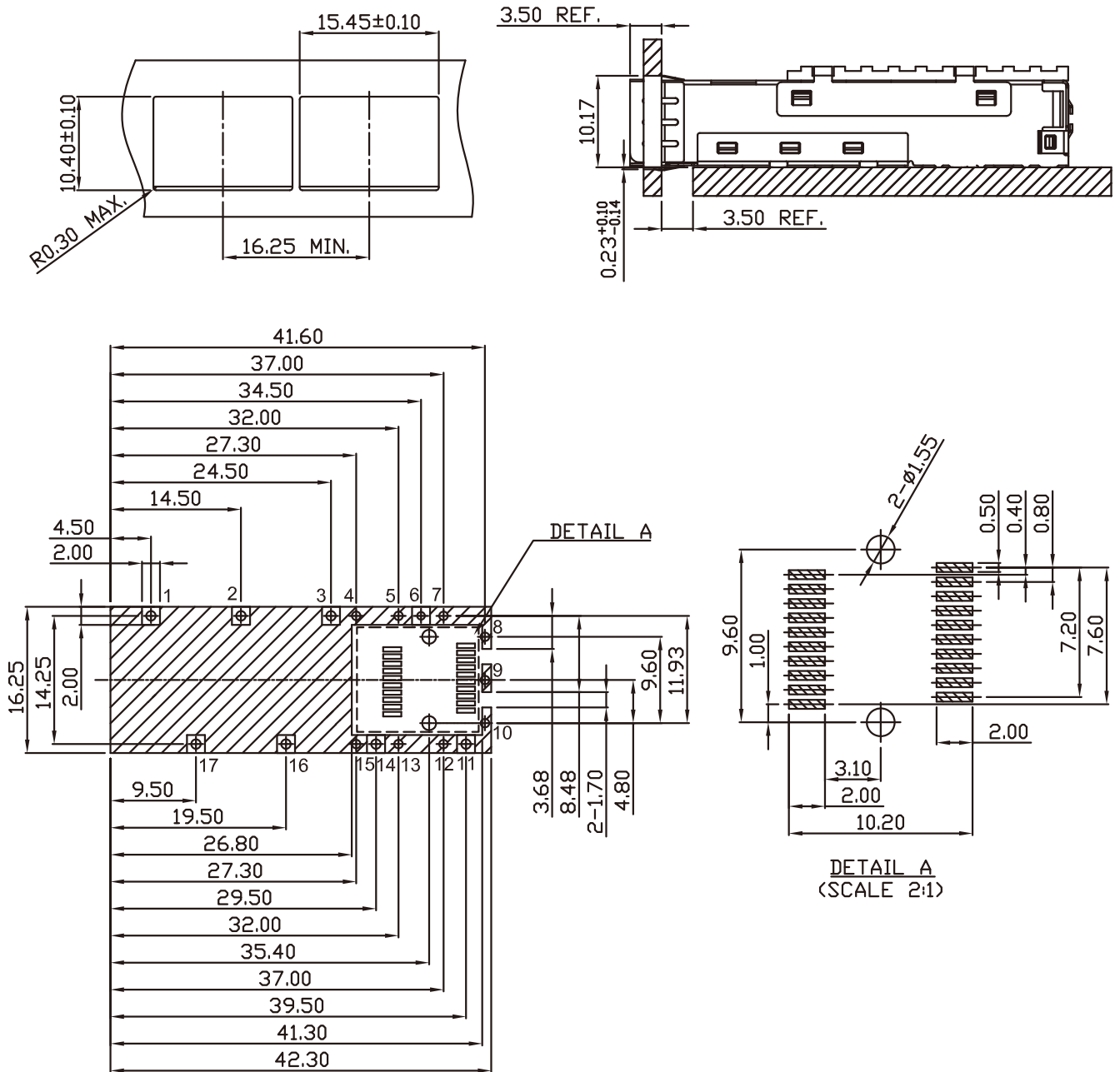


INTERCONNECT SOLUTION FOR OCP 3.0 NIC

Enablement for rapid technology development
Simplifying design decisions

PCB LAYOUT

KSFP-A-PPFA-0125-XXX

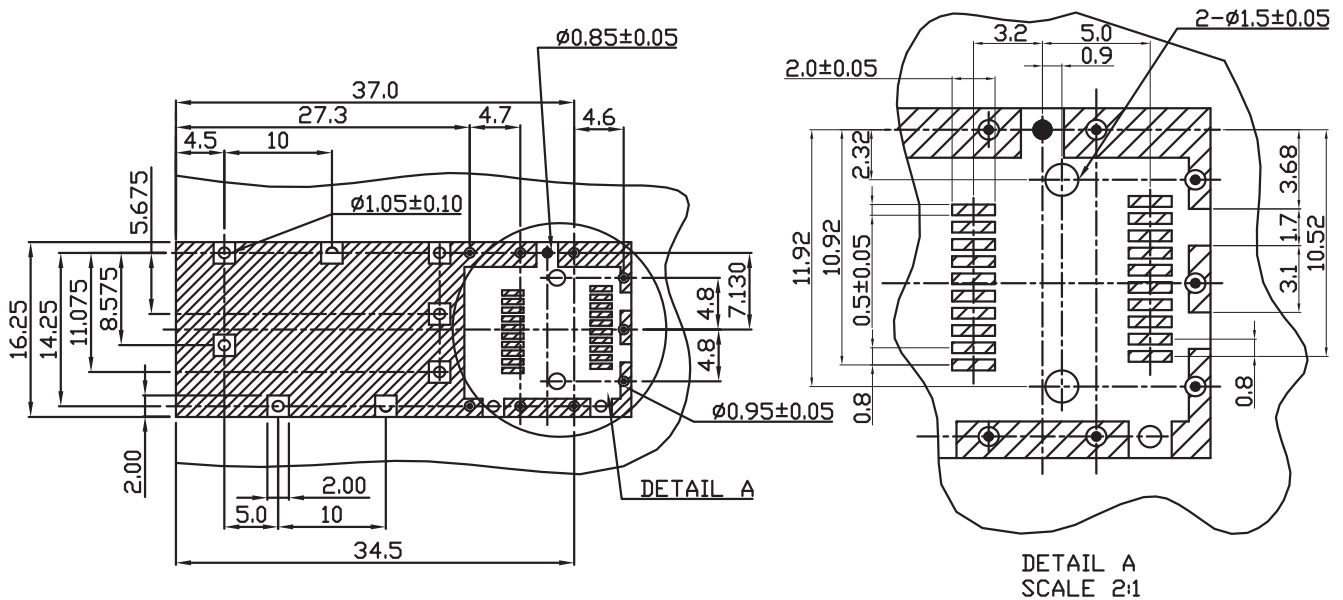
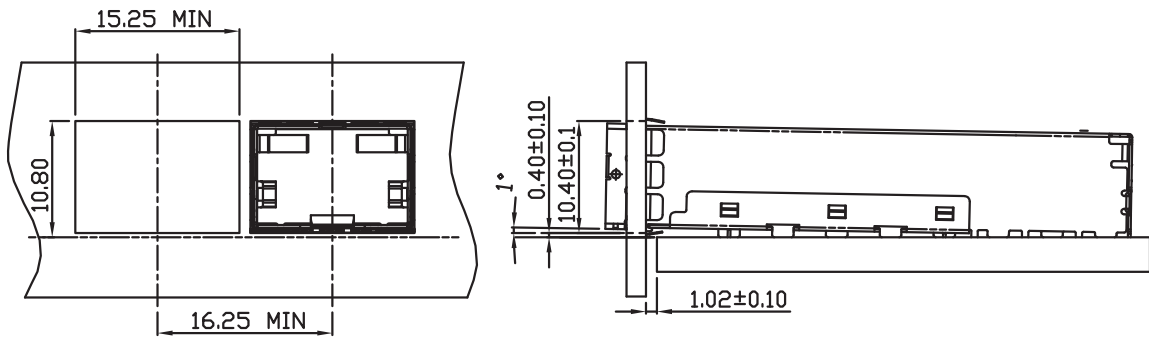


INTERCONNECT SOLUTION FOR OCP 3.0 NIC

Enablement for rapid technology development
Simplifying design decisions

PCB LAYOUT

KSFP-A-PPFB-0105-XXX

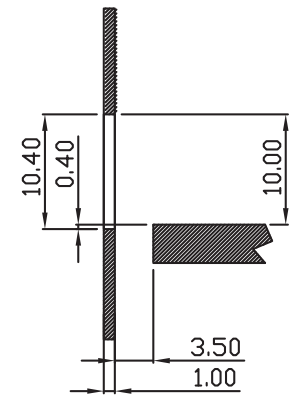
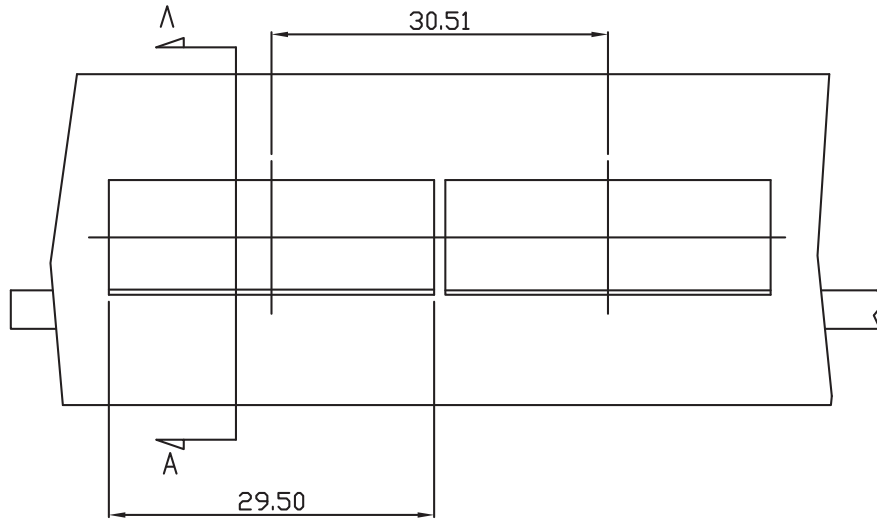


INTERCONNECT SOLUTION FOR OCP 3.0 NIC

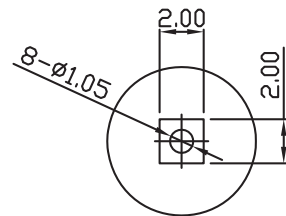
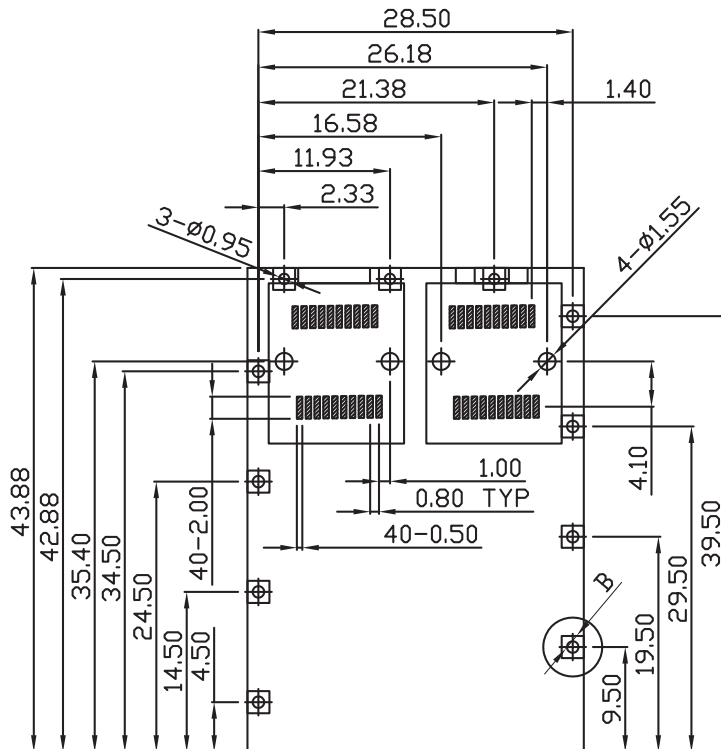
Enablement for rapid technology development
Simplifying design decisions

PCB LAYOUT

KSFP-A-PSLB-0202-XXX



SECTION A-A



DETAIL B

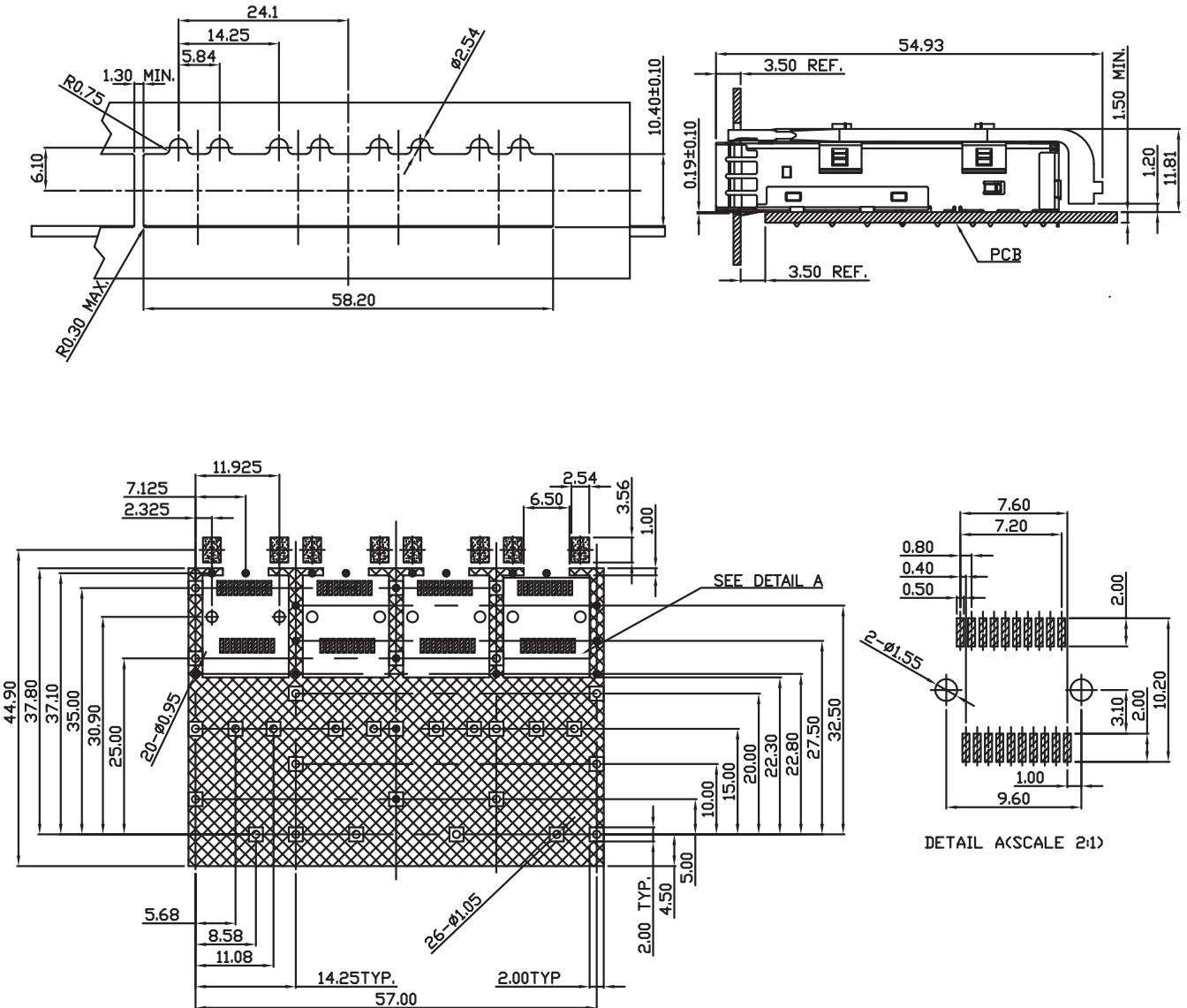
P.C.B LAYOUT
TOP VIEW ±0.05

INTERCONNECT SOLUTION FOR OCP 3.0 NIC

Enablement for rapid technology development
Simplifying design decisions

PCB LAYOUT

KSFP-A-PPFA-0412-XXX

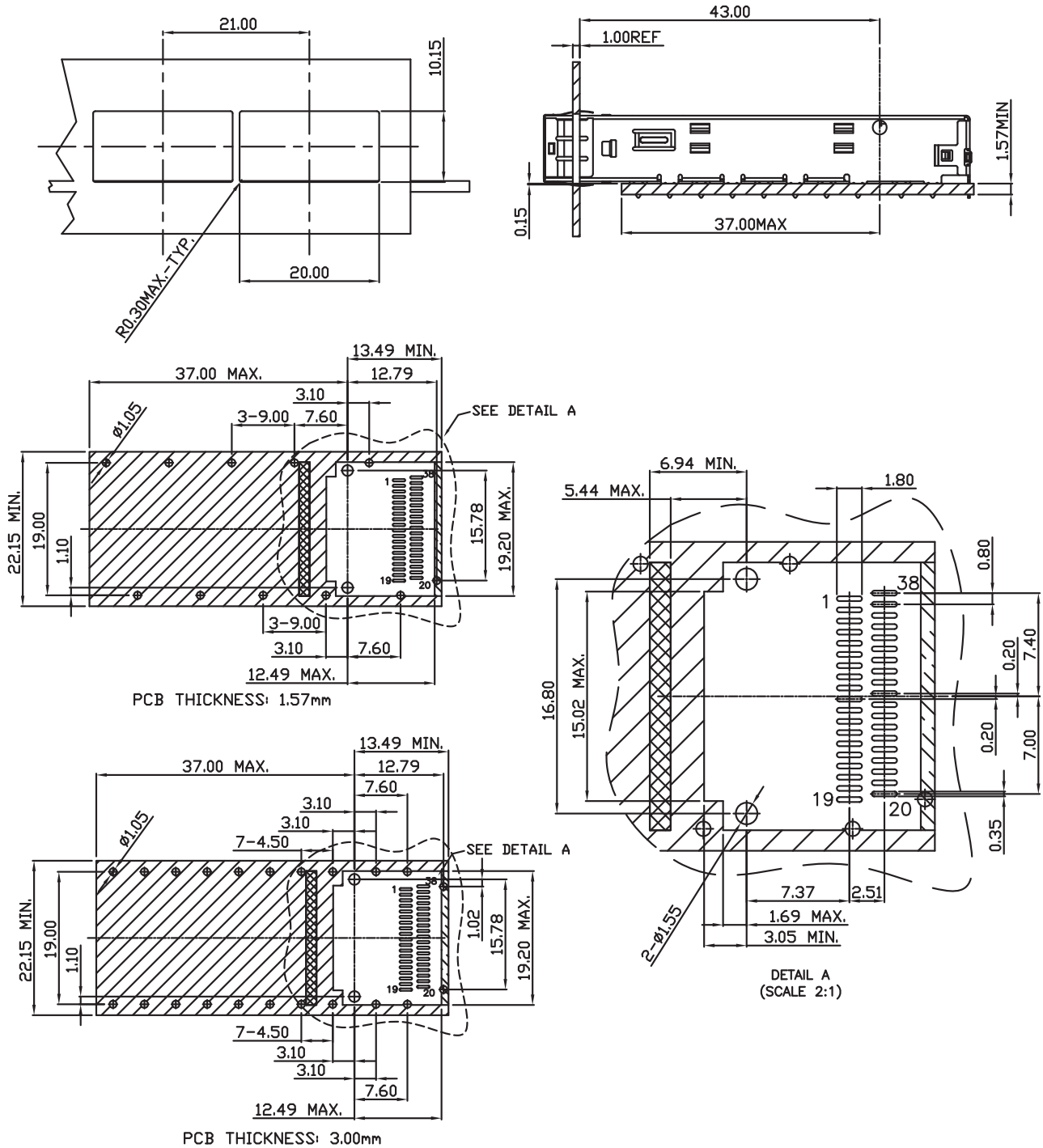


INTERCONNECT SOLUTION FOR OCP 3.0 NIC

Enablement for rapid technology development
Simplifying design decisions

PCB LAYOUT

KQFP-A-ZPFT-0101-XXX



INTERCONNECT SOLUTION FOR OCP 3.0 NIC

Enablement for rapid technology development
Simplifying design decisions

PCB LAYOUT

KQFP-A-ZPFT-01P1-XXX

